

*a  
conced.*

a first insulative material, having a relatively low dielectric constant, positioned to electrically isolate members of the first upper level from one another and extending to the lower level of interconnect members; and

*Reasons  
for allowance*

a second insulative material, having a relatively high dielectric constant, positioned to electrically isolate members of the lower level from [some of] the electronic device [devices].

✓ In Claim 5, line 2, before "insulative material", change "lower" to -- second --.

✓ In claim 7, at line 4, add a period to the end of the claim as follows: after the second occurrence of "interconnect", change "members" to -- members. -- .

#### REMARKS

Claims 1 - 33 remain in the application. Claims 22 - 33 have been withdrawn from examination under a restriction requirement which is traversed herein. Claims 1 - 21 have been rejected, and claims 7 and 8 are the subject of objection. Objection has also been raised to the drawings.

Reconsideration is requested in view of the above amendments and the argument which follows.

#### Removal of the Restriction Requirement

The Examiner has suggested a restriction requirement, segregating claims 1 - 21 into a Group I and claims 22 - 33 into a Group II. Although a provisional election has been made to prosecute the claims of Group I, the restriction is respectfully traversed for the following reasons.

The office action states that a device of Group I could result from selectively depositing the second insulating layer so that no etching is necessary after depositing the upper layer of interconnect members. While such may be theoretically possible, it is